
USB HIGH-SIDE POWER SWITCH

NO.EA-168-080912

OUTLINE

The R5523N Series is CMOS-based high-side MOSFET switch IC for Universal Serial Bus (USB) applications. Low ON Resistance (Typ.130mΩ) and low supply current (Typ.20μA at active mode) are realized in this IC.

An over-current limit circuit, a thermal shutdown circuit, and an under voltage lockout (UVLO) circuit are built-in as protection circuits. Further, a delay circuit for flag signal after detecting over-current, is embedded to prevent miss-operation of error flag because of inrush current. The R5523N Series is ideal for applications of protection for USB power supply. Since the package is small SOT-23-5, high density mounting on board is possible.

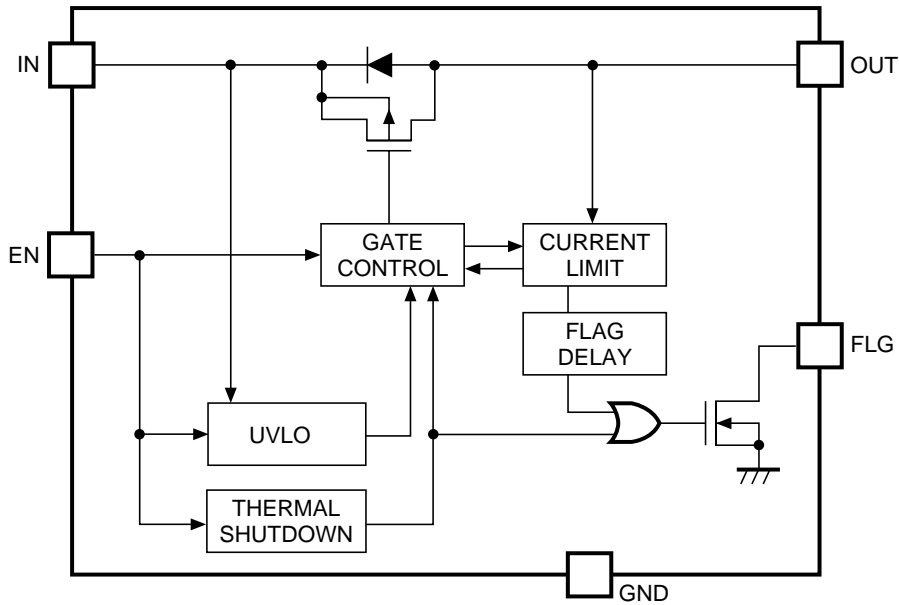
FEATURES

- Built-in P-channel MOSFET Switch
- Supply Current Typ. 20μA (at Active Mode)
- Switch ON Resistance Typ. 130mΩ
- Output Current Min. 500mA
- Flag Delay Time Typ. 10ms.
- Package SOT-23-5
- Over- Current Limit / Short Circuit Protection
- Built-in Under Voltage Lockout (UVLO) Function
- Built-in Thermal Shutdown Protection
- Built-in Soft-start Function

APPLICATIONS

- USB Peripherals
- Notebook PCs

BLOCK DIAGRAM



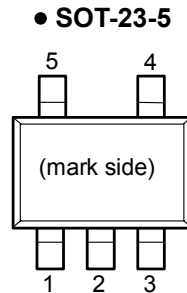
SELECTION GUIDE

The output current and the logic of the enable pin for the ICs can be selected at the user's request. The selection can be made with designating the part number as shown below;

R5523Nxxxx-xx-X ←Part Number
 ↑ ↑ ↑ ↑ ↑
 a b c d e

Code	Contents
a	Designation of Package Type: N: SOT-23-5
b	Designation of the output current. 001: 500mA
c	Designation of the logic of the enable pin. A: active with "L" B: active with "H"
d	Designation of Taping Type: TR (Refer to the taping specifications.)
e	Designation of composition of pin plating: -F: Lead free solder plating (SOT-23-5)

PIN CONFIGURATIONS



PIN DESCRIPTION

Pin No	Symbol	Pin Description
1	EN	Enable Pin
2	GND	Ground Pin
3	FLG	FLG pin (Open Drain Output)
4	V _{IN}	Power Supply Pin
5	V _{OUT}	Output Pin

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit
V _{IN}	Input Voltage	6.5	V
V _{EN}	Enable Pin Input Voltage	-0.3 to V _{IN} +0.3	V
V _{FLG}	Flag Voltage	-0.3 to 6.5	V
I _{FLG}	Flag Current	14	mA
V _{OUT}	Output Voltage	-0.3 to V _{IN} +0.3	V
I _{OUT}	Output Current	Internal Limited	
P _D	Power Dissipation (SOT-23-5) *Note1	420	mW
T _{opt}	Operating Temperature	-40 to +85	°C
T _{stg}	Storage Temperature	-55 to +125	°C

*Note1) For Power Dissipation please refer to PACKAGE INFORMATION to be described.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field.

The functional operation at or over these absolute maximum ratings is not assured.

ELECTRICAL CHARACTERISTICS

• R5523N001A/B

(T_{opt}=25°C)

Symbol	Item	Conditions	MIN.	TYP.	MAX.	Unit
V _{IN}	Input Voltage		2.2		5.5	V
I _{DD1}	Supply Current 1	V _{OUT} =open * ¹		20	45	μA
I _{DD2}	Supply Current 2	V _{OUT} =open * ²		0.1	1.0	μA
R _{ON}	Switch On Resistance	V _{IN} =5V, I _{OUT} =500mA		130	180	mΩ
t _{on}	Output Turn-on Delay	V _{IN} =5V, R _L =60Ω		1400		μs
t _{off}	Output Turn-off Delay	V _{IN} =5V, R _L =60Ω		5		μs
V _{UVLO}	UVLO Threshold	V _{IN} =increasing	1.6	1.9		V
V _{HYS}	UVLO Hysteresis Range	V _{IN} =decreasing		0.1		V
I _{TH}	Current Limit Threshold			1.0	1.5	A
I _{lim}	Short Current Limit	V _{OUT} =0V	0.5	0.75	1.3	A
t _{FD}	Over Current Flag Delay	From Over Current to FLG= "L"	5	10	20	ms
T _{TS}	Thermal Shutdown Temperature Threshold	T _J =increasing		135		°C
		T _J =decreasing		120		°C
I _{EN}	Enable Pin Input Current			0.01	1.0	μA
V _{EN1}	Enable Pin Input Voltage 1	V _{EN} =increasing	2.0			V
V _{EN2}	Enable Pin Input Voltage 2	V _{EN} =decreasing			0.8	V
I _{LO}	Output Leakage Current			0.1	1.0	μA
V _{LF}	Flag "L" Output Voltage	I _{SINK} =1mA			0.4	V
I _{FOF}	Flag Off Current	V _{FLG} =5.5V		0.01	1.0	μA

*1) EN= "L" (R5523NxxxA), EN= "H" (R5523NxxxB)

*2) EN= "H" (R5523NxxxA), EN= "L" (R5523NxxxB)

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions.

The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge.

And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

OPERATION

This explanation is based on the typical application.

- There is a parasitic diode between source and drain of the switch transistor. (Refer to the block diagram.) Because of this, in both cases of enable and disable, if the voltage of V_{OUT} pin is higher than V_{IN} pin, current flows from V_{OUT} to V_{IN} .
- In case that V_{OUT} pin and GND is short, if over-current would continue, the temperature of the IC would increase drastically. If the temperature of the IC is beyond 135°C , the switch transistor turns off and the FLG pin level becomes "L". Then, when the temperature of the IC decreases equal or lower than 120°C , the switch transistor turns on and FLG becomes "H". Unless the abnormal situation of V_{OUT} pin is removed, the switch transistor repeats on and off. Refer to the 24) Thermal Shutdown operation in the typical characteristics.
- Over-current level is set internally in the IC. There are three types of response against over-current: Under the condition that V_{OUT} pin is short or large capacity is loaded, if the IC is enabled, the IC becomes constant current state. After the flag delay time passes, FLG becomes "L", that means over current state. Refer to the 23) current limit transient response of typical characteristics. While the switch transistor is on, if V_{OUT} pin is short or large capacity is loaded, until the current limit circuit responds, large transient current flows. After the transient current is beyond the over-current detector threshold and delay time of the flag passes, FLG becomes "L", that means over current state. Refer to the 25), 26) over-current limit transient response of typical characteristics. In the case that load current gradually increases, the IC is not into the constant current state until the current is beyond over current limit. Once the level is beyond the over current detector threshold, load current is limited into over current limit level. Note that load current continuously flows until the load current is beyond the over-current detector threshold.
- FLG pin is Nch Open drain output. If the over-current or over-temperature is detected, FLG becomes "L". If over-current is detected, FLG becomes "L" after the flag delay time t_{FD} passes. Therefore flag signal is not out with inrush current.
- UVLO circuit prevents that the switch transistor turns on until the input voltage is beyond 1.9V. UVLO circuit can operate when the IC is enabled.

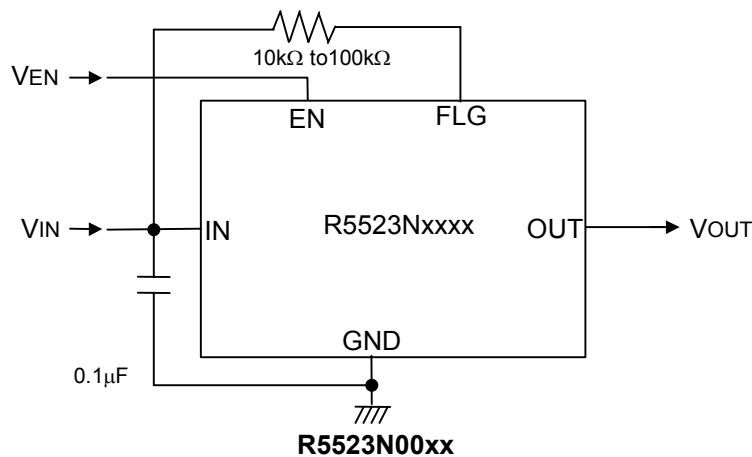
TYPICAL APPLICATION AND TECHNICAL NOTES

• Bypass capacitor

- Put a capacitance range from 0.1 μ F to 1 μ F bypass capacitor between V_{IN} pin and GND pin of the IC. Without a bypass capacitor, in case of output short, because of the high side inductance of V_{IN} pin, the ringing may be generated and it might be a cause of an unstable operation.

• Pull-up resistance value range of flag pin

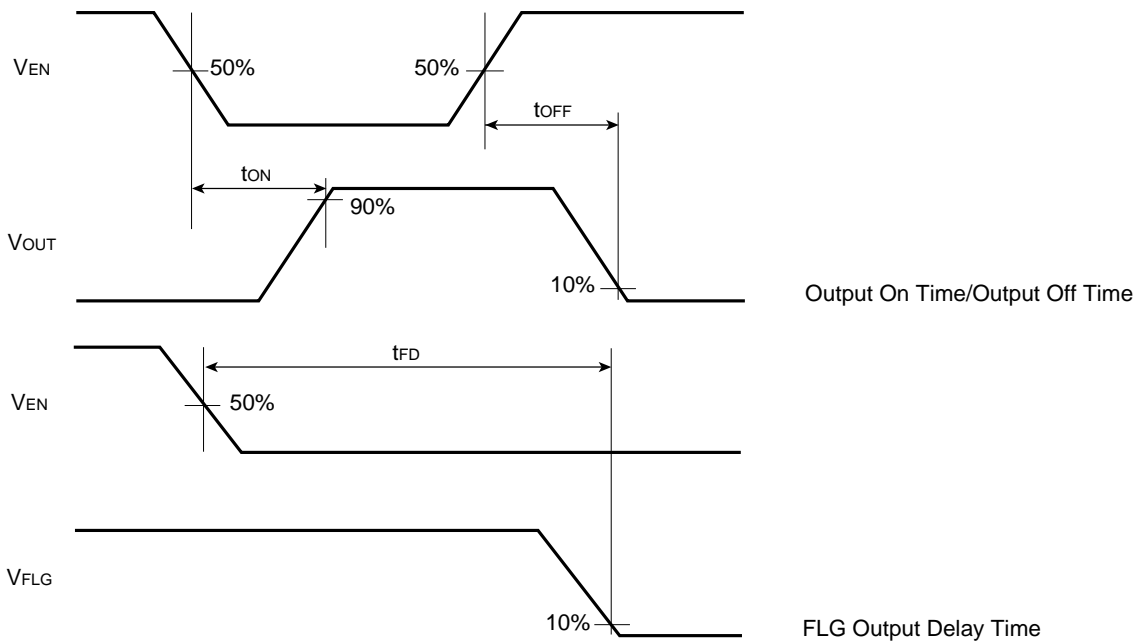
- Recommended pull-up resistance value range of flag pin is from 10k Ω to 100k Ω .



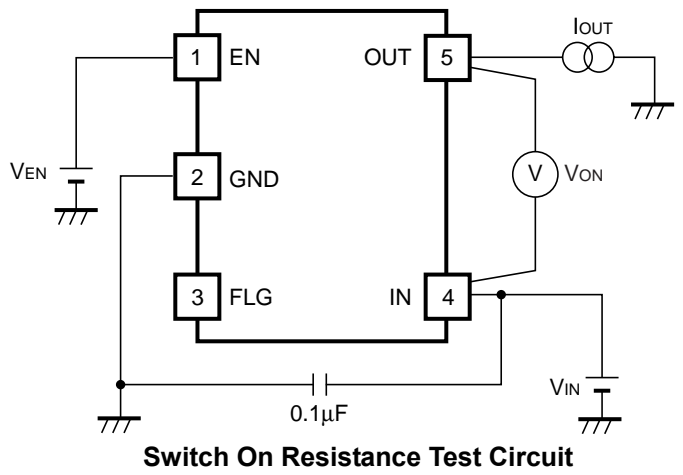
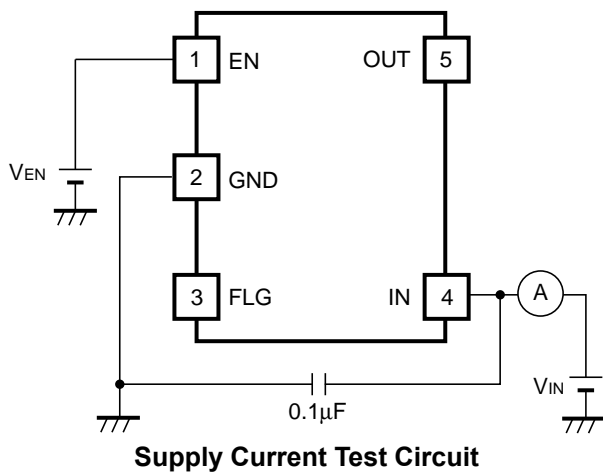
• Over-current limit Function

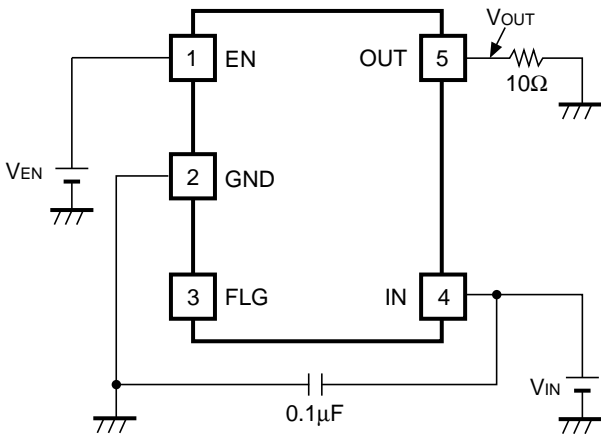
In case that V_{OUT} pin and GND is short, if over-current would continue, the temperature of the IC would increase drastically. If the temperature of the IC is equal or more than 135°C (Typ.), the switch transistor turns off because of thermal shutdown protection. In other words, when the temperature of the IC becomes equal or more than 135°C (Typ.), both the over-current limit circuit and thermal shutdown circuit work for the protection of the IC.

TIMING CHART

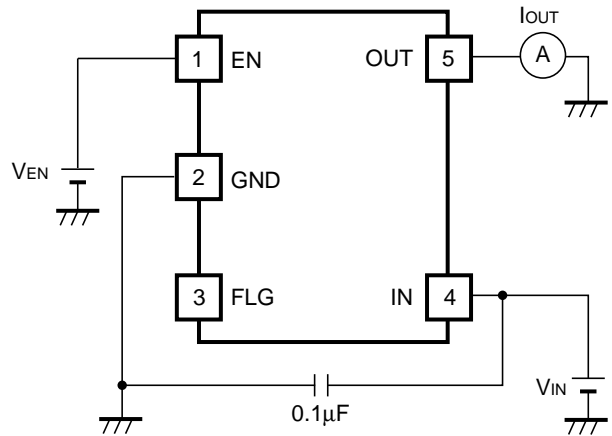


TEST CIRCUITS

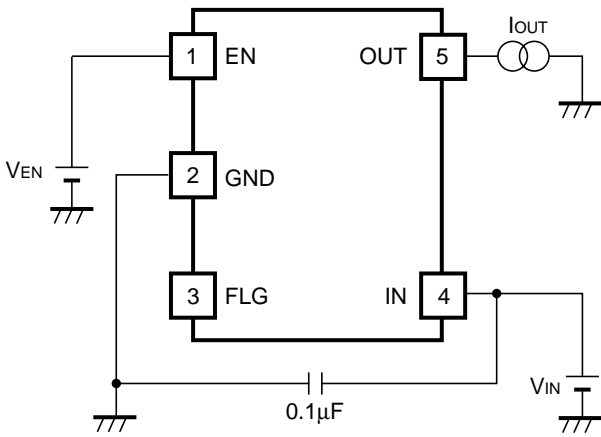




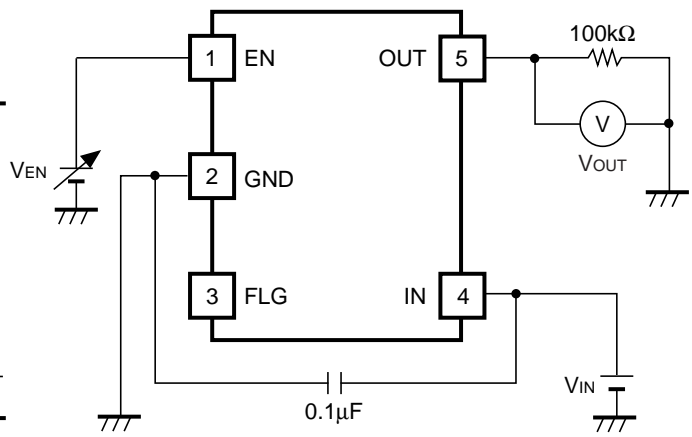
Output On Time Test Circuit



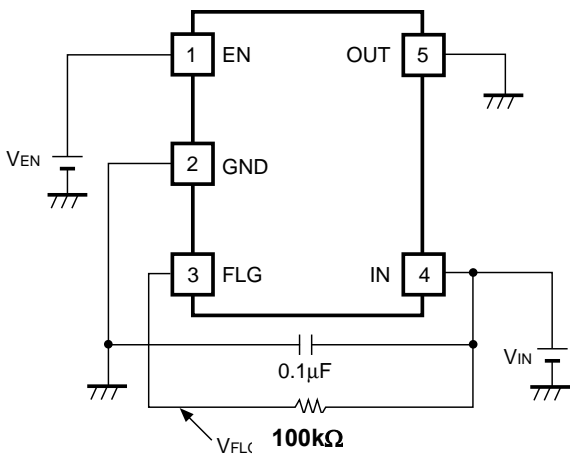
Over-current Limit Test Circuit



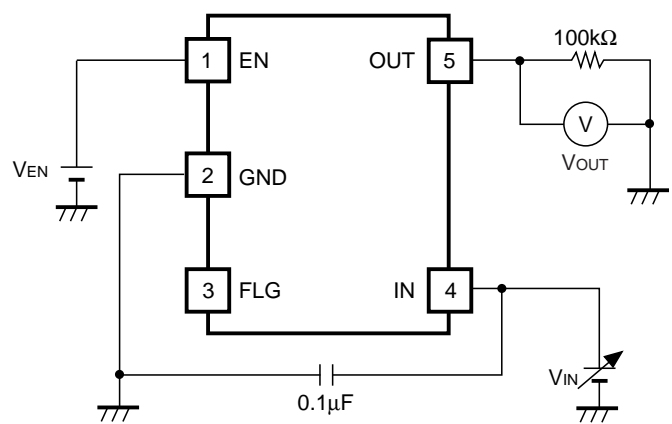
Over-current Threshold Test Circuit



Enable Input Voltage



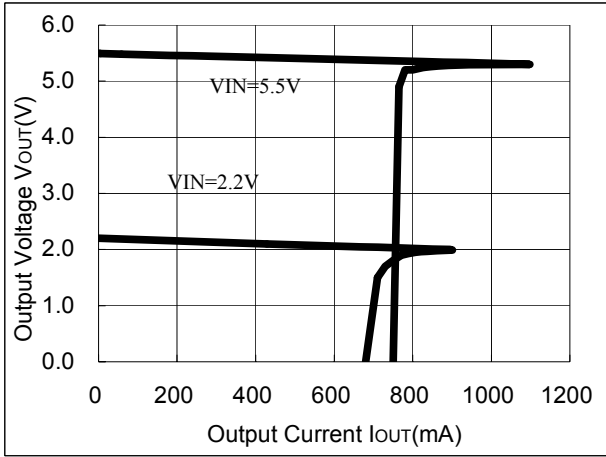
Flag Output Delay Time Test



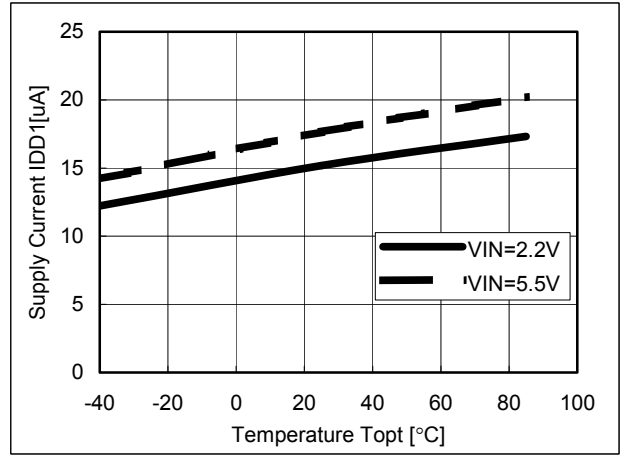
UVLO Threshold Test

TYPICAL CHARACTERISTICS

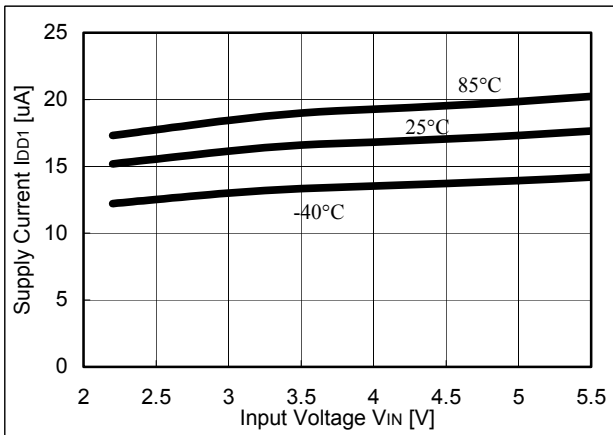
1) Output Voltage vs. Output Current



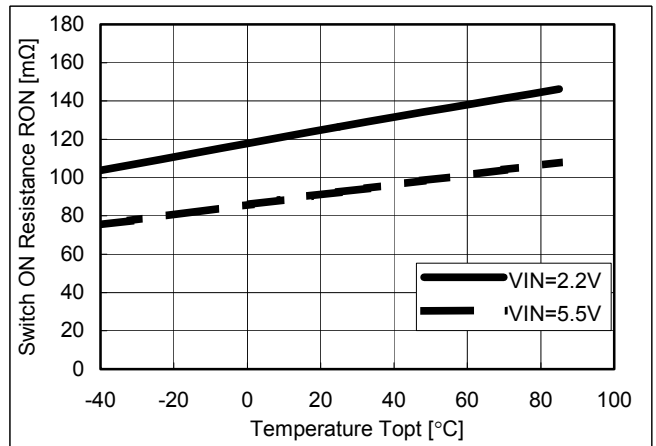
2) Supply Current vs. Temperature



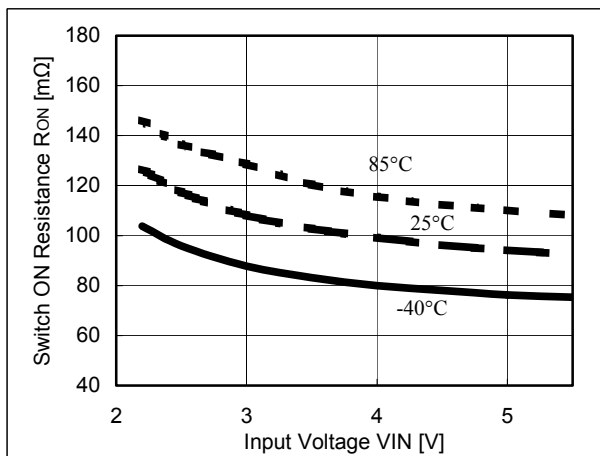
3) Supply Current vs. Input Voltage



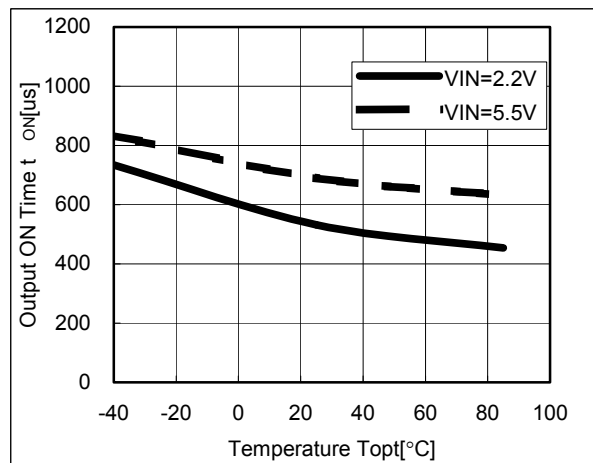
4) On Resistance vs. Temperature



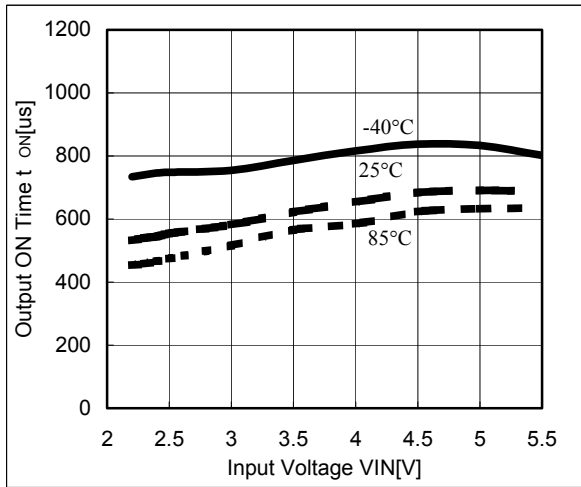
5) On Resistance vs. Input Voltage



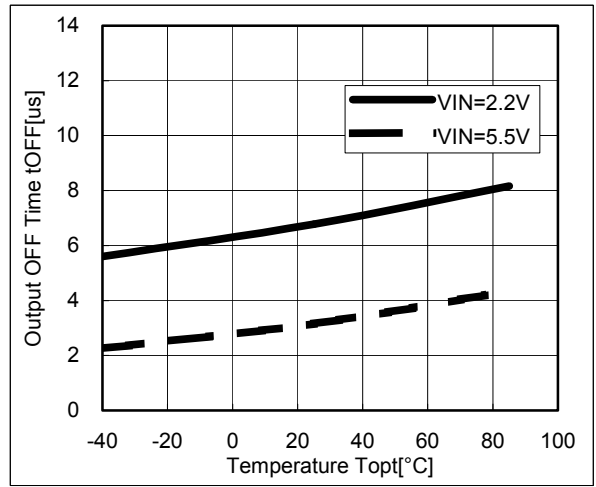
6) Output On Time vs. Temperature



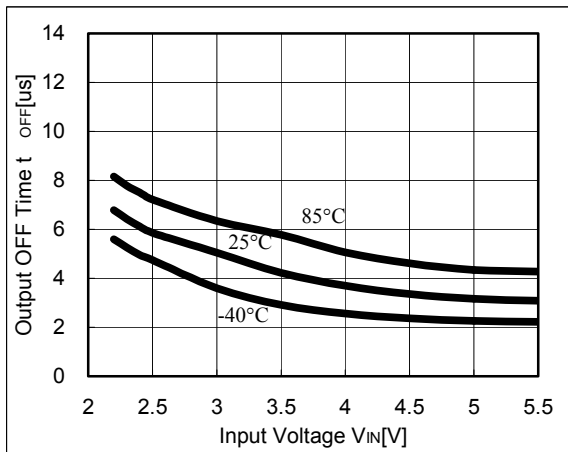
7) Output On Time vs. Input Voltage



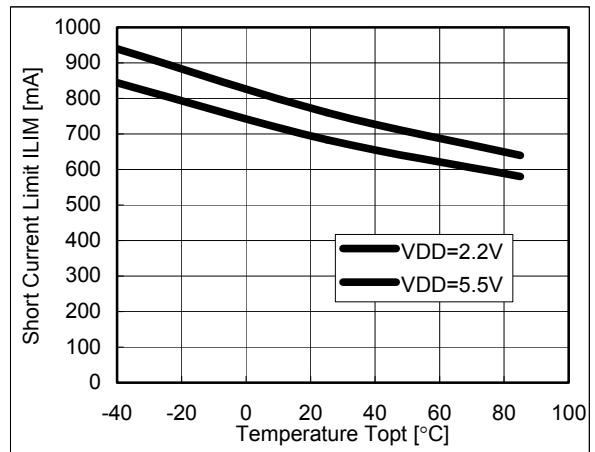
8) Output Off Time vs. Temperature



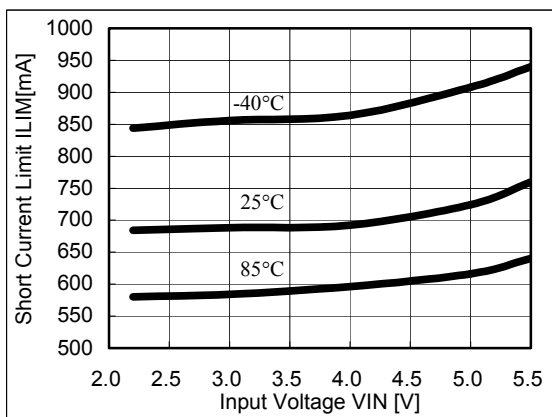
9) Output Off Time vs. Input Voltage



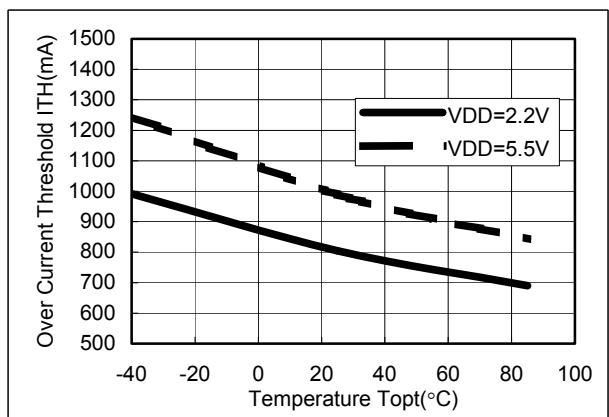
10) Short-current Limit vs. Temperature



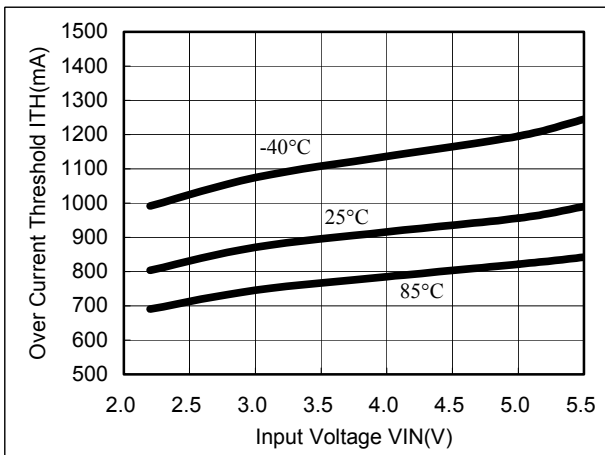
11) Short Current Limit vs. Input Voltage



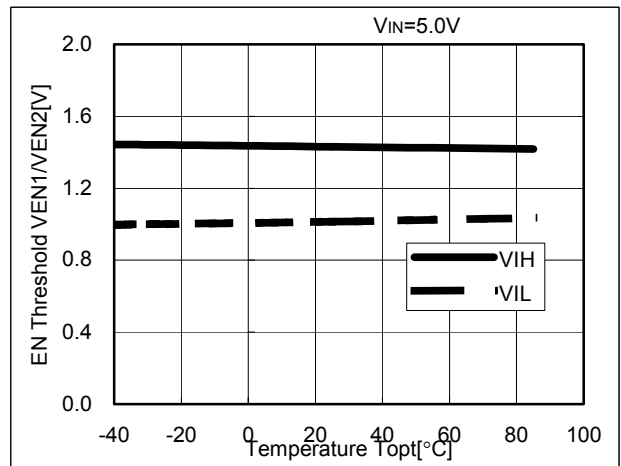
12) Over Current Threshold vs. Temperature



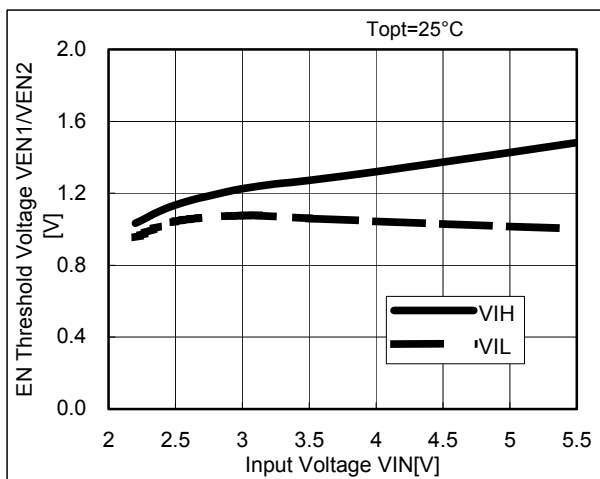
13) Over Current Threshold vs. Input Voltage



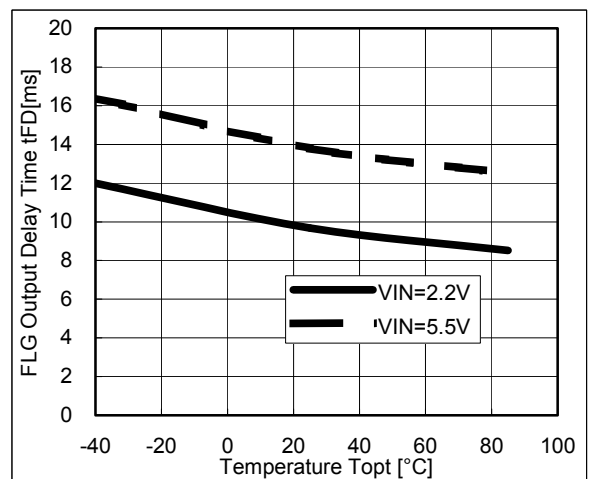
14) Enable Input Voltage vs. Temperature



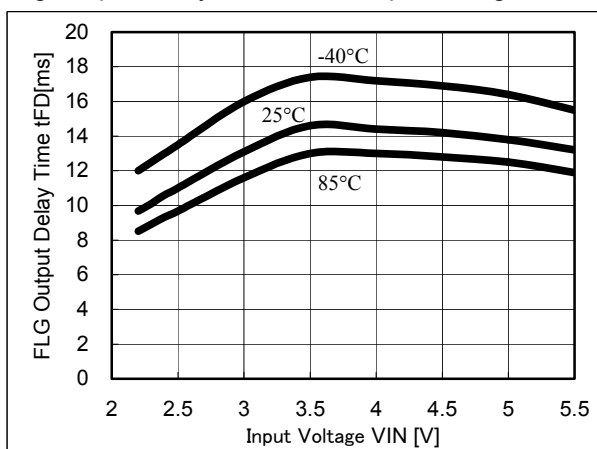
15) Enable Input Voltage vs. VIN Input Voltage



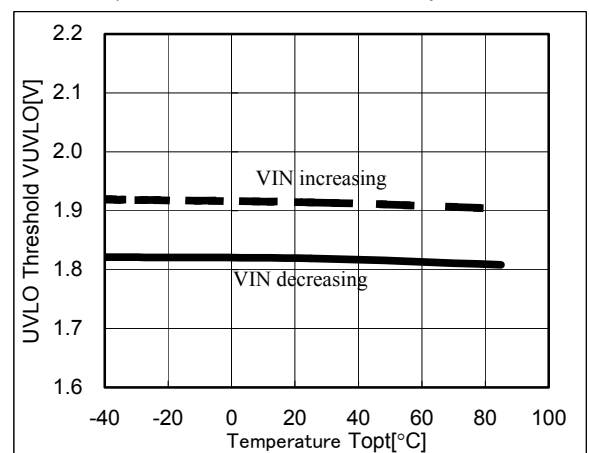
16) Flag Output Delay Time vs. Temperature



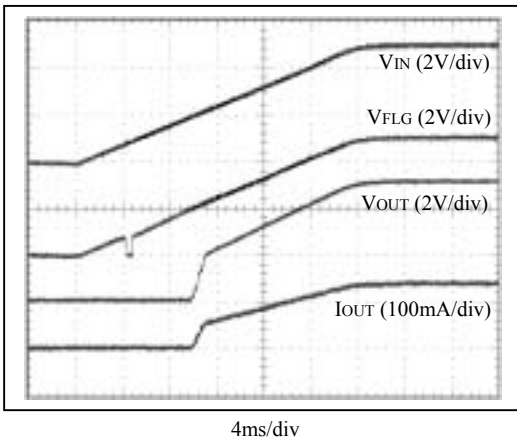
17) Flag Output Delay Time vs. VIN Input Voltage



18) UVLO Threshold vs. Temperature

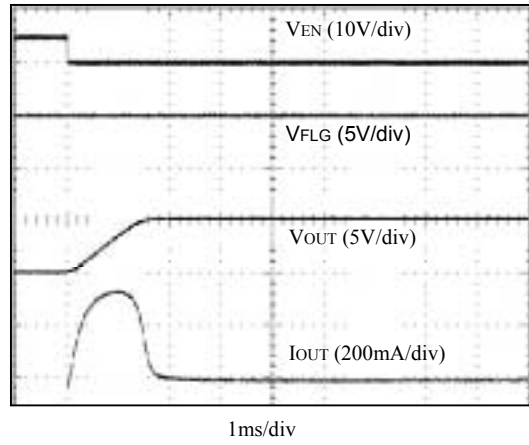


19) UVLO Characteristic at V_{IN} increasing
 $V_{EN}=0V, C_L=47\mu F, R_L=35\Omega$



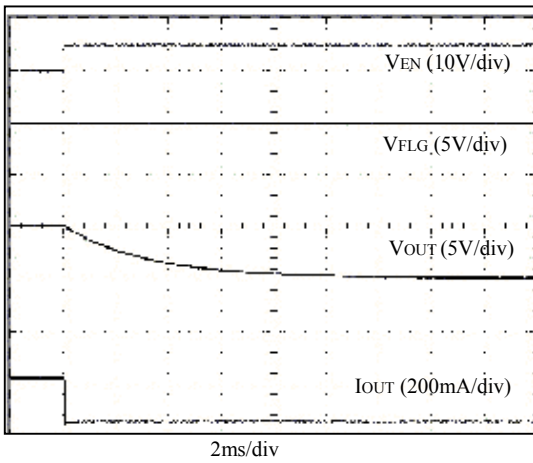
20) Turn on Response

$V_{IN}=5V, C_L=47\mu F, R_L=35\Omega$



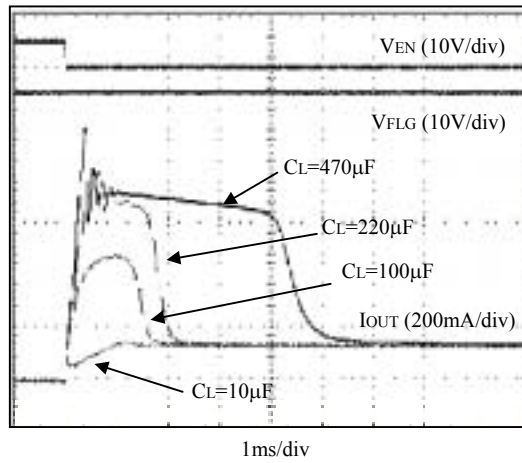
21) Turn off Response

$V_{IN}=5V, C_L=47\mu F, R_L=35\Omega$



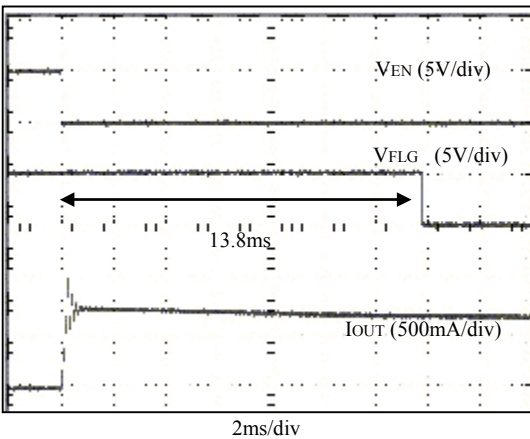
22) Inrush current

$V_{IN}=5V, R_L=35\Omega$



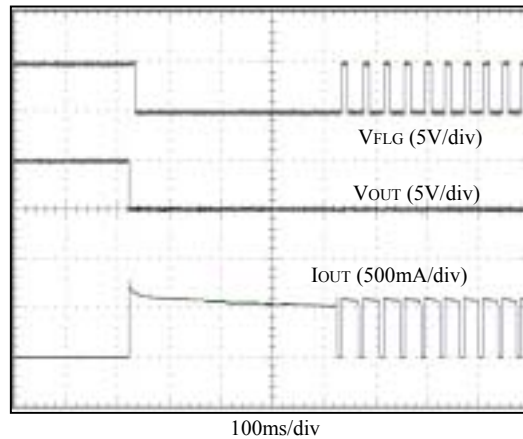
23) Current Limit Transient Response
 (Case: Enable to Short)

$V_{IN}=5V$

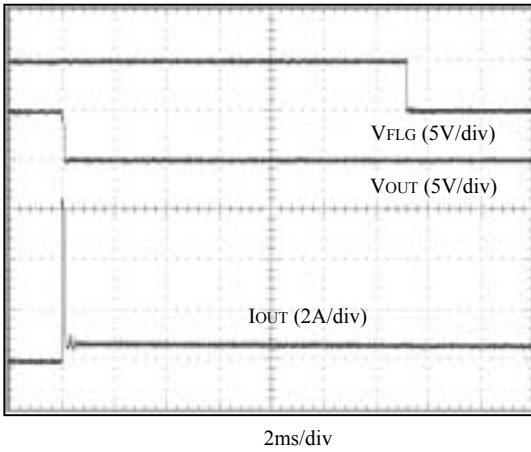


24) Thermal Shutdown Operation

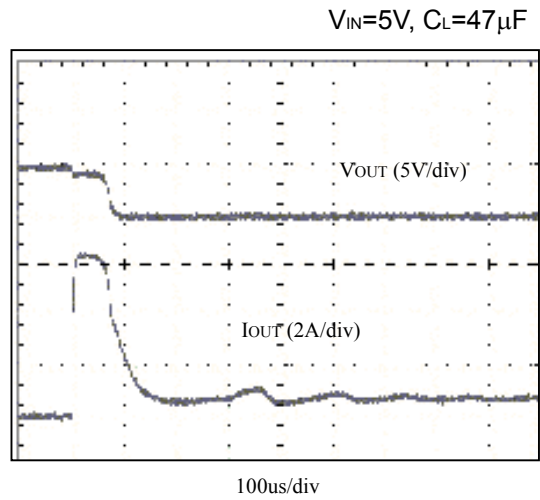
$V_{IN}=5V, C_L=47\mu F$



25) Current Limit Transient Response
(Case: Output short during enable)
 $V_{IN}=5V$, $C_L=47\mu F$



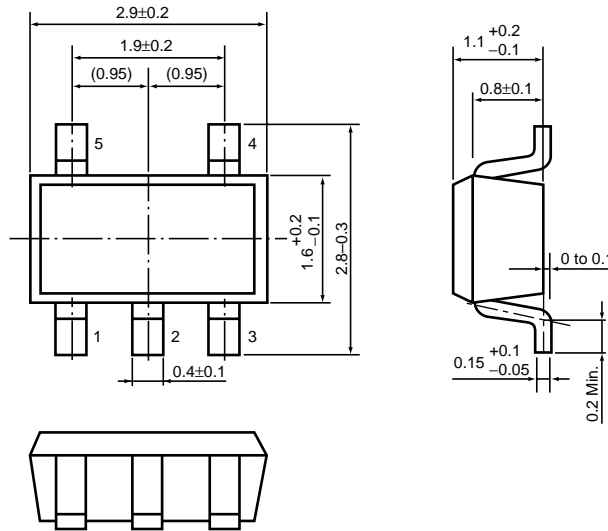
26) Zoomed in 25)



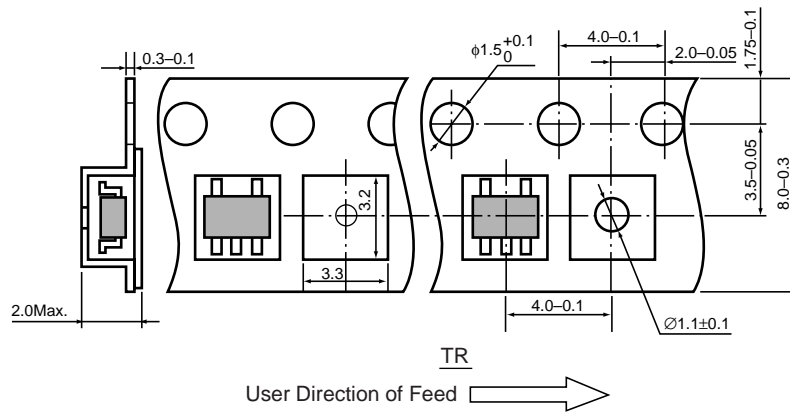
- SOT-23-5 (SC-74A)

Unit: mm

PACKAGE DIMENSIONS

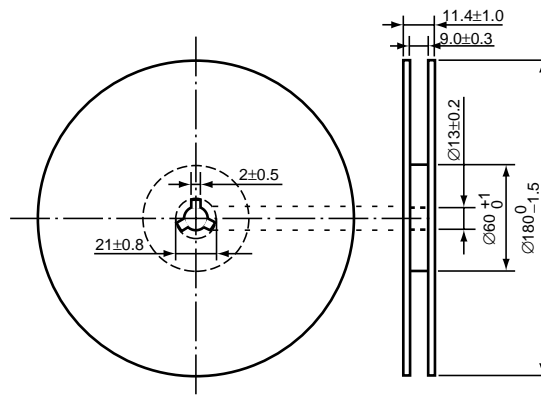


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=3000pcs)



POWER DISSIPATION (SOT-23-5)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

(Power Dissipation (SOT-23-5) is substitution of SOT-23-6.)

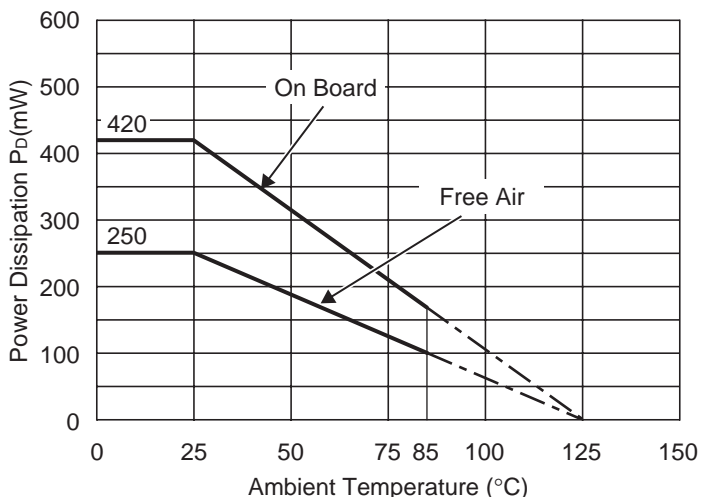
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

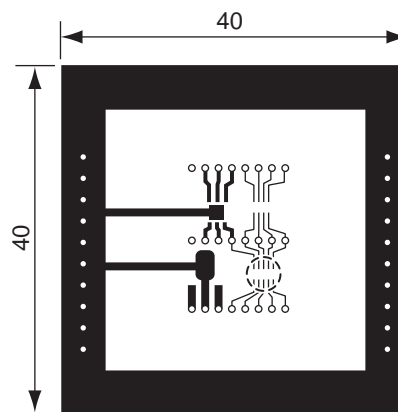
Measurement Result

($T_{opt}=25^{\circ}\text{C}$, $T_{jmax}=125^{\circ}\text{C}$)

	Standard Land Pattern	Free Air
Power Dissipation	420mW	250mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.42\text{W}=238^{\circ}\text{C/W}$	400 $^{\circ}\text{C/W}$



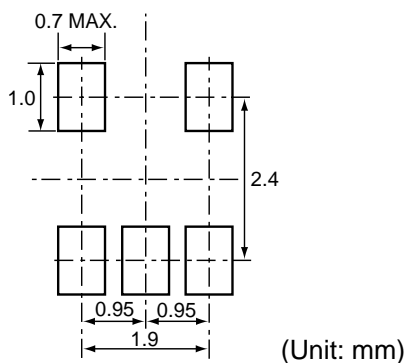
Power Dissipation



Measurement Board Pattern

○ IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN



(Unit: mm)